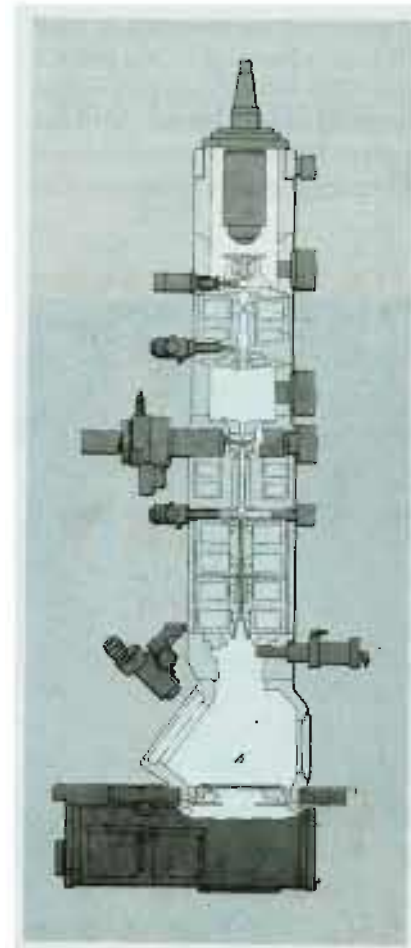
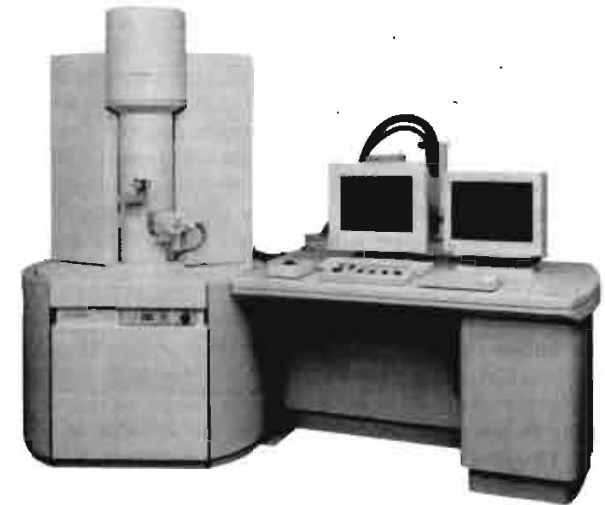
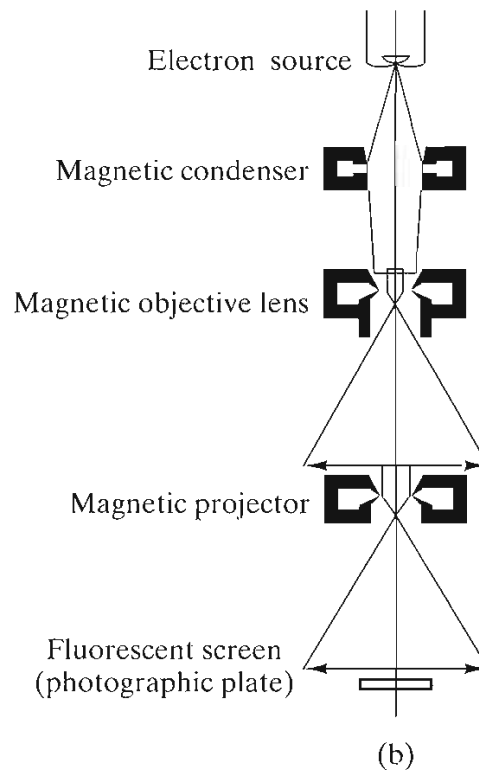
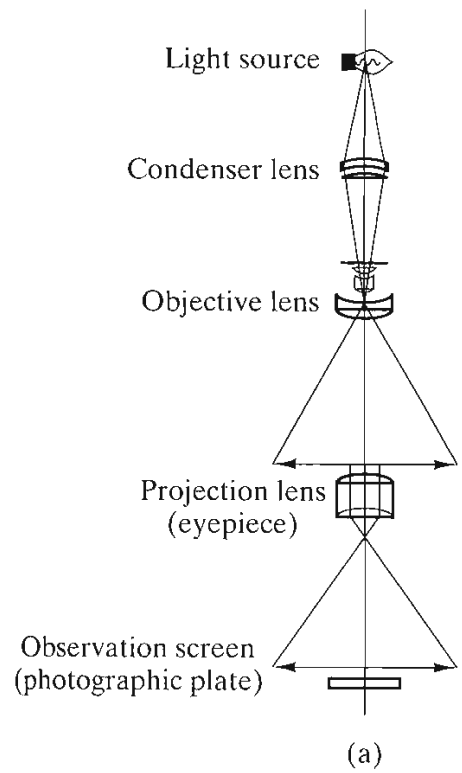
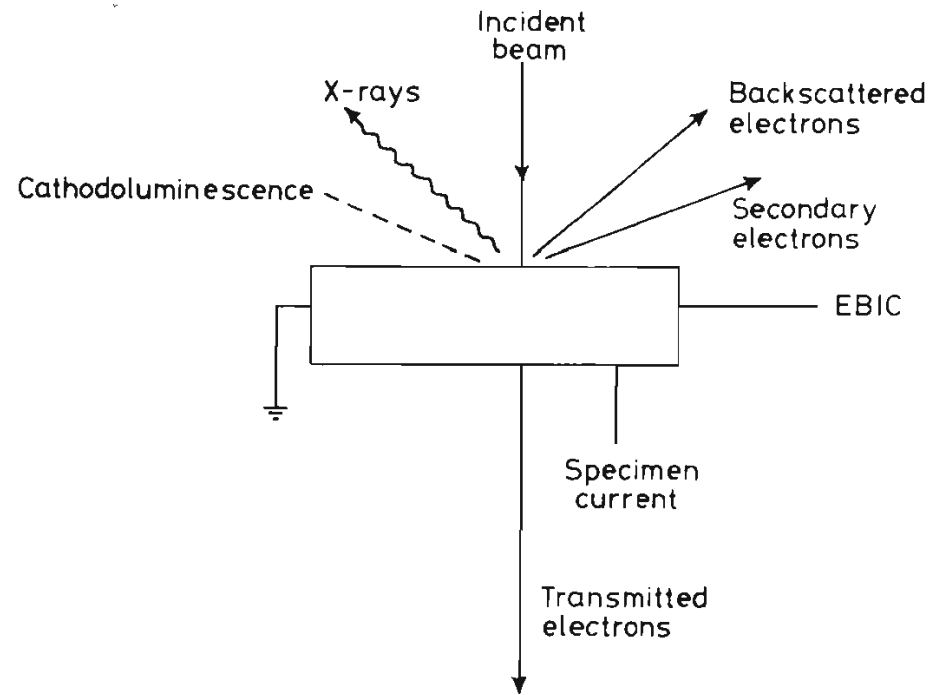


## Transmission electron microscope (TEM)

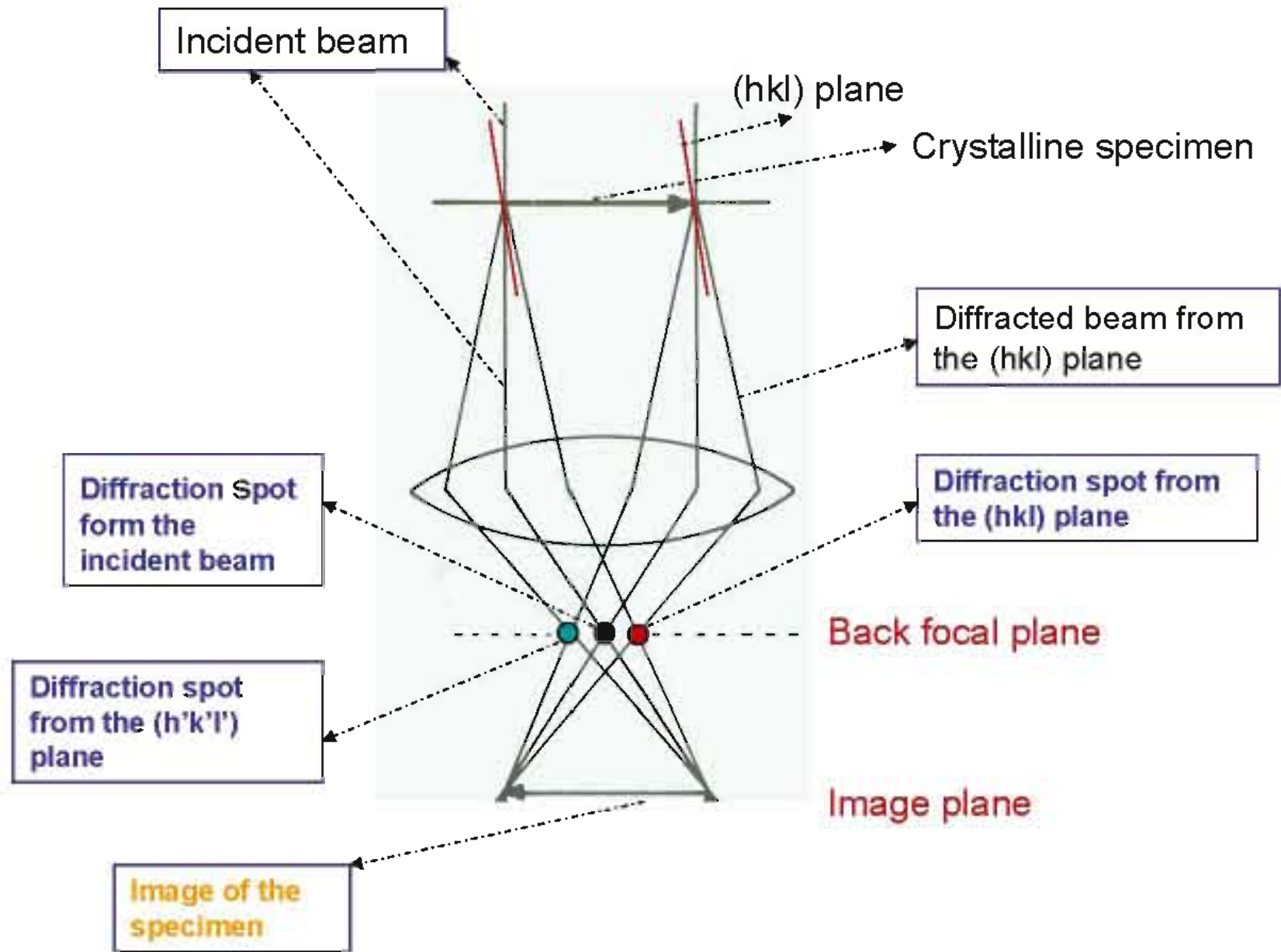




**Similarity in design between (a) an optical microscope and (b) a transmission electron microscope.**



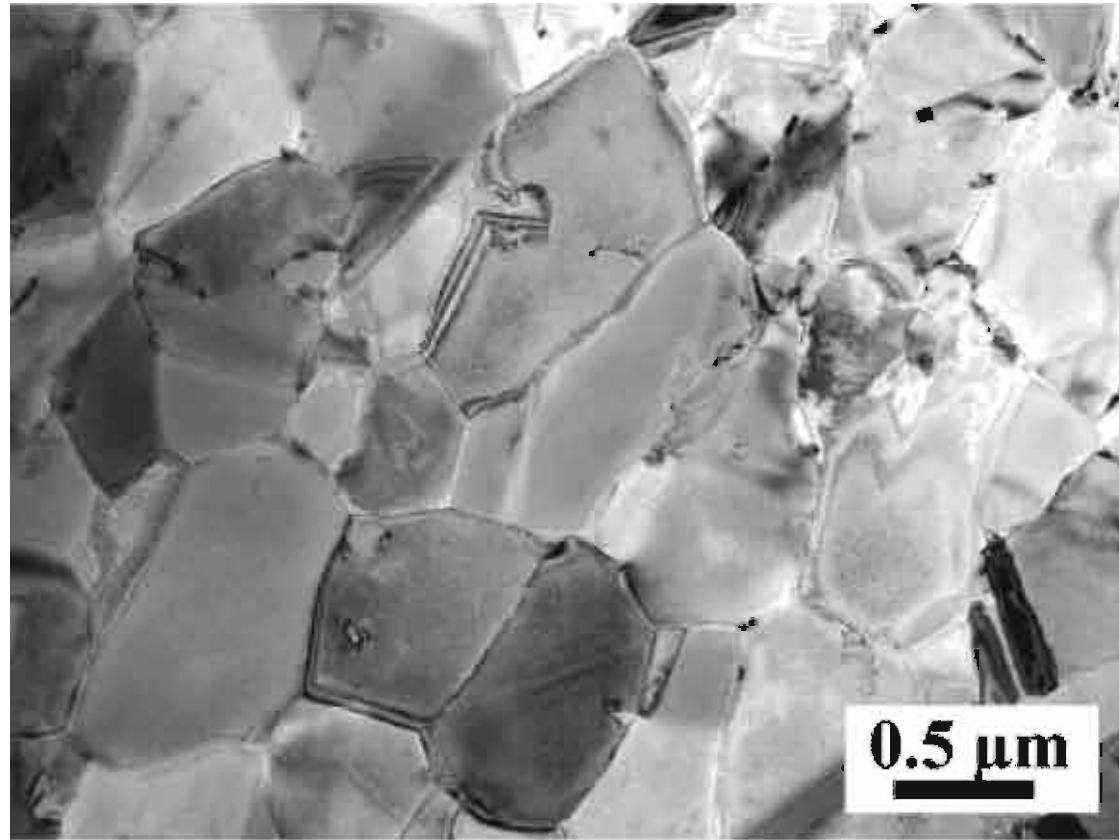
## Interaction between the electron beam and the materials

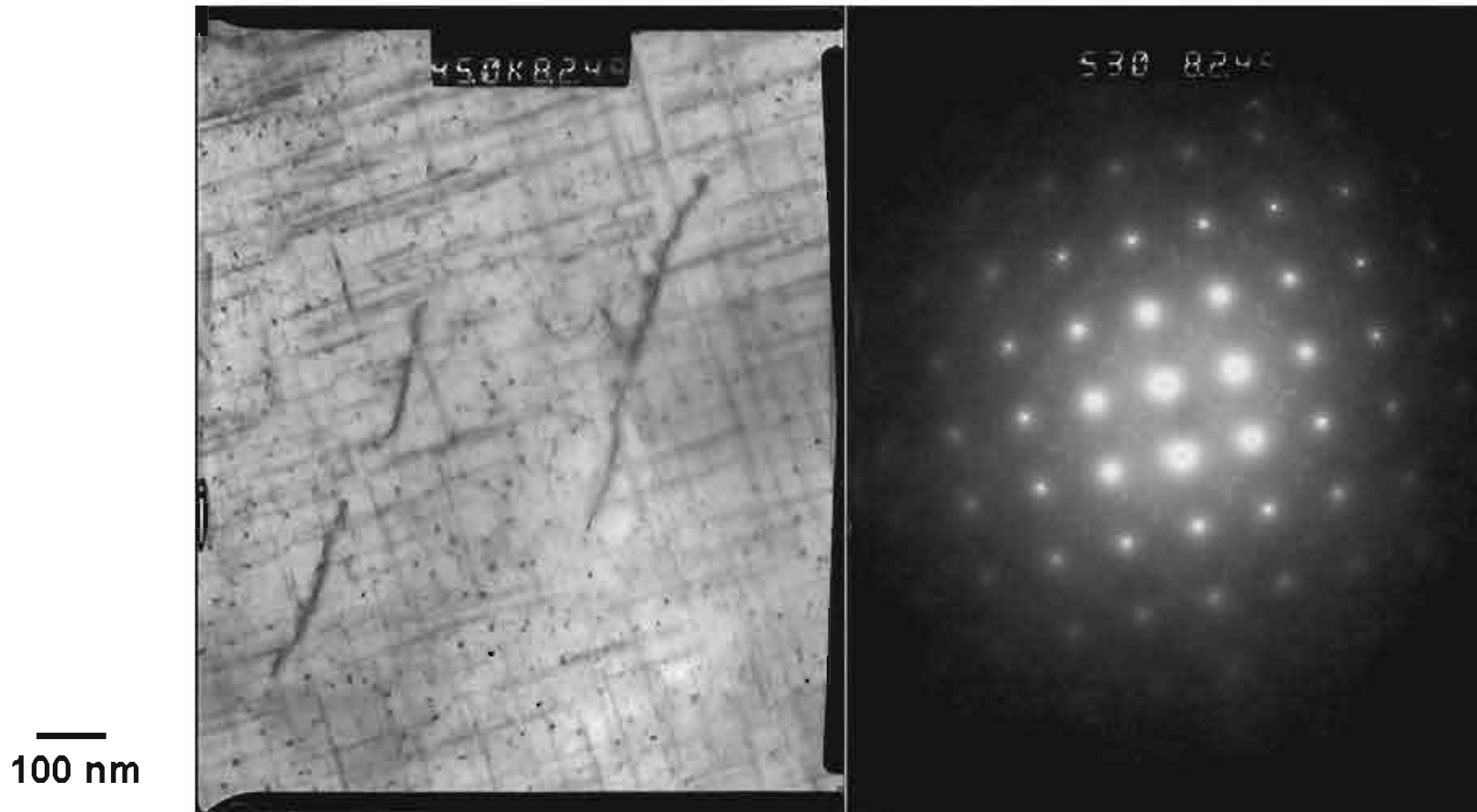


**Formation of the diffraction pattern and the image in the TEM**

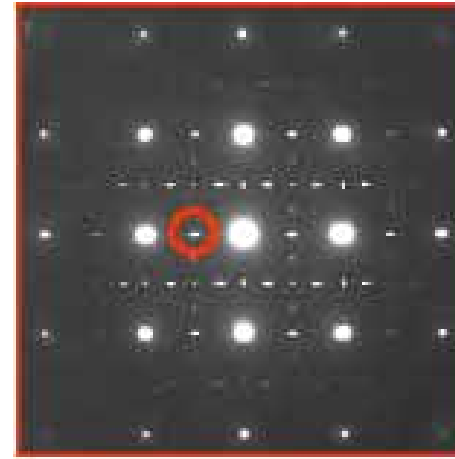


**Electron diffraction pattern**



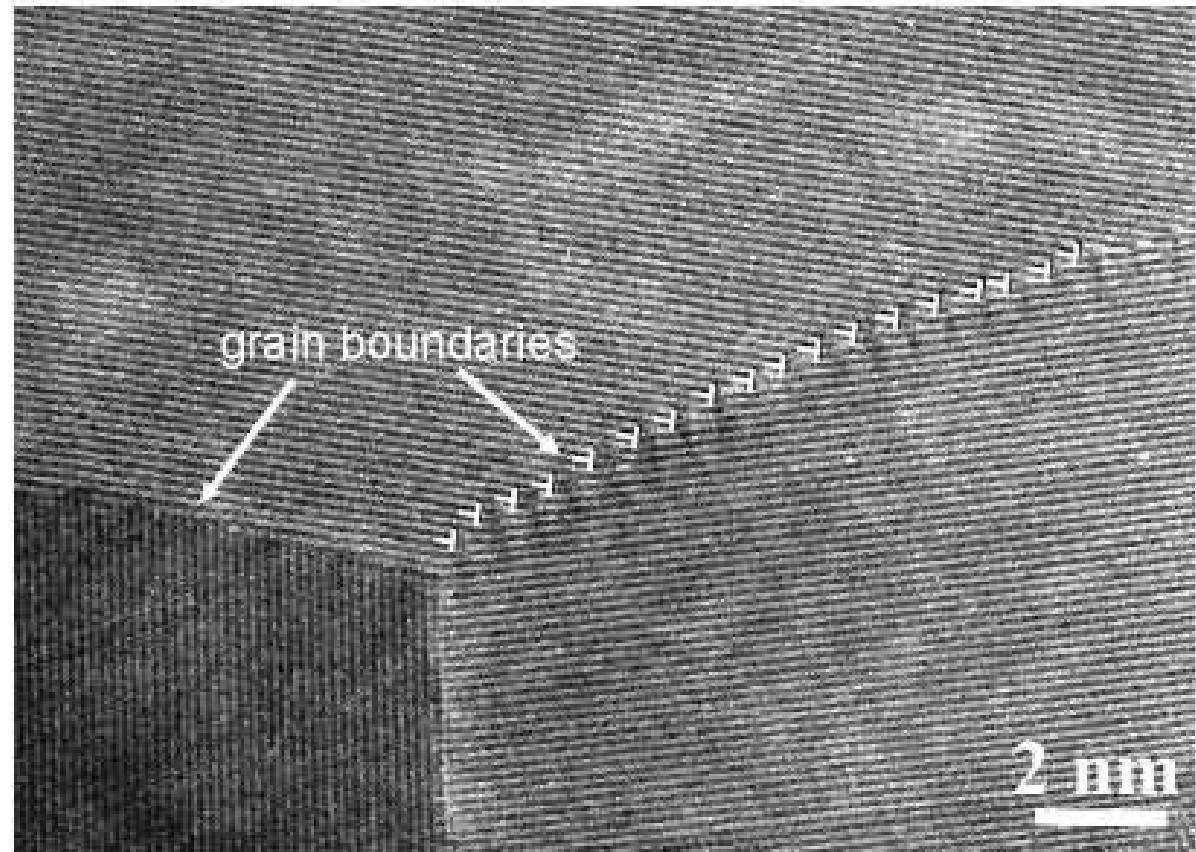


**Precipitates formed in an Al alloy (a) bright field image; (b) diffraction pattern from the area in (a).**



Precipitates formed in a spray-formed IN 718 aged at 750°C for 24h; TEM, (4918)





**High resolution images formed in the TEM.**

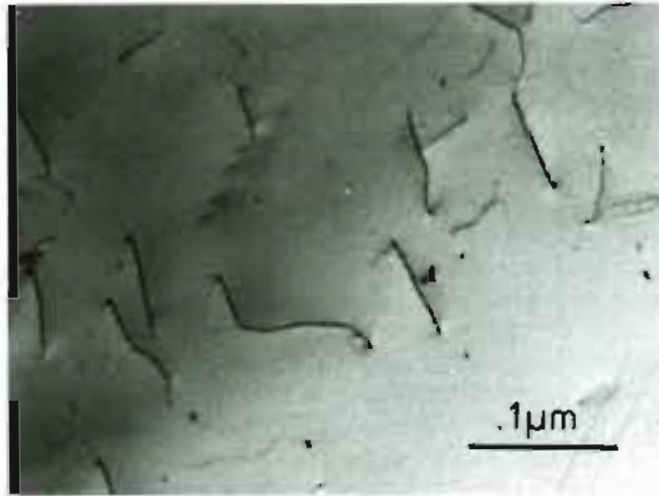
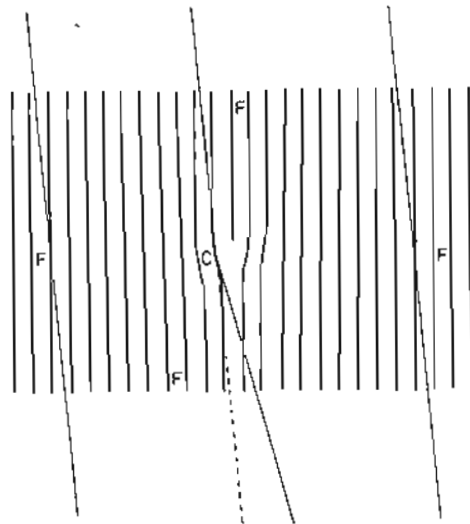
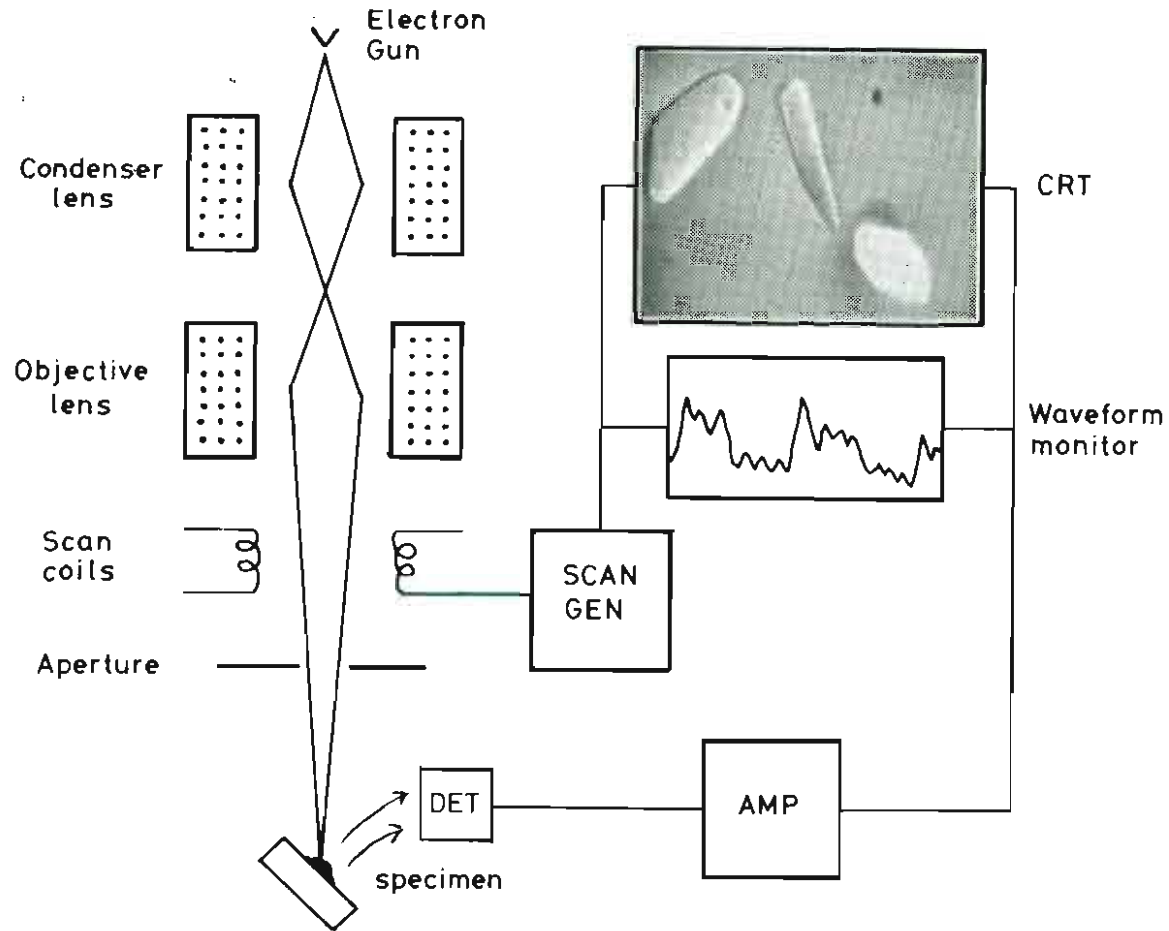


Figure 4.22 Dislocations in strong diffraction contrast in a metal foil.



# Scanning electron microscope

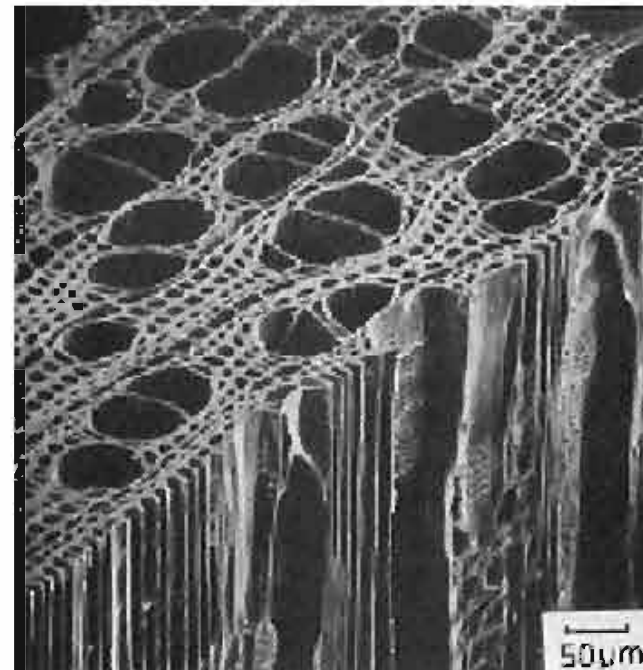
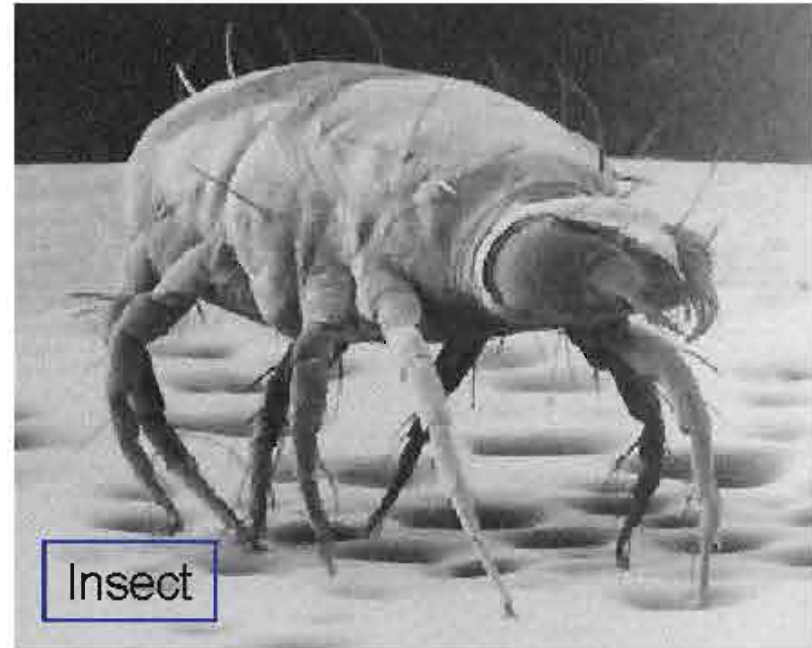




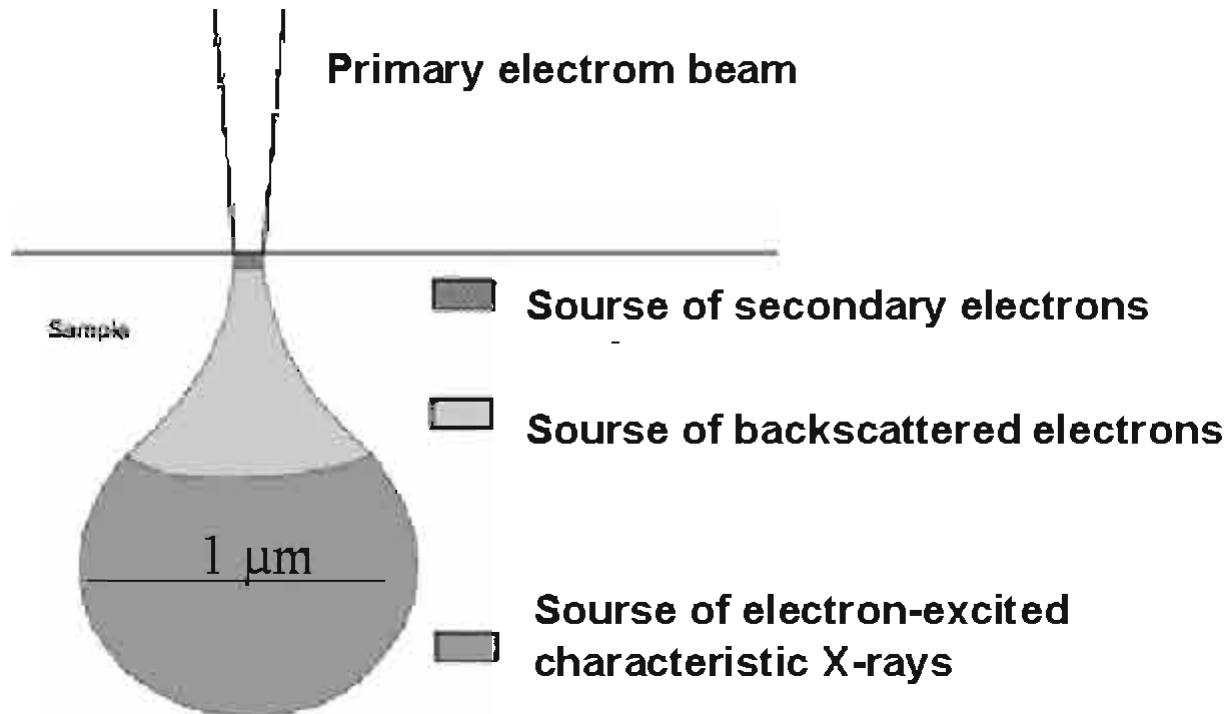
**Schematic diagram showing the main component of a scanning electron microscope**

## SEM advantages

1. Resolution
2. Depth of focus
3. Chemical analysis

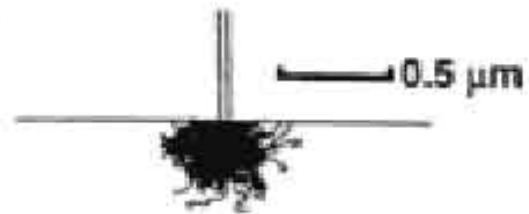


## Beam – specimen interaction 20kV

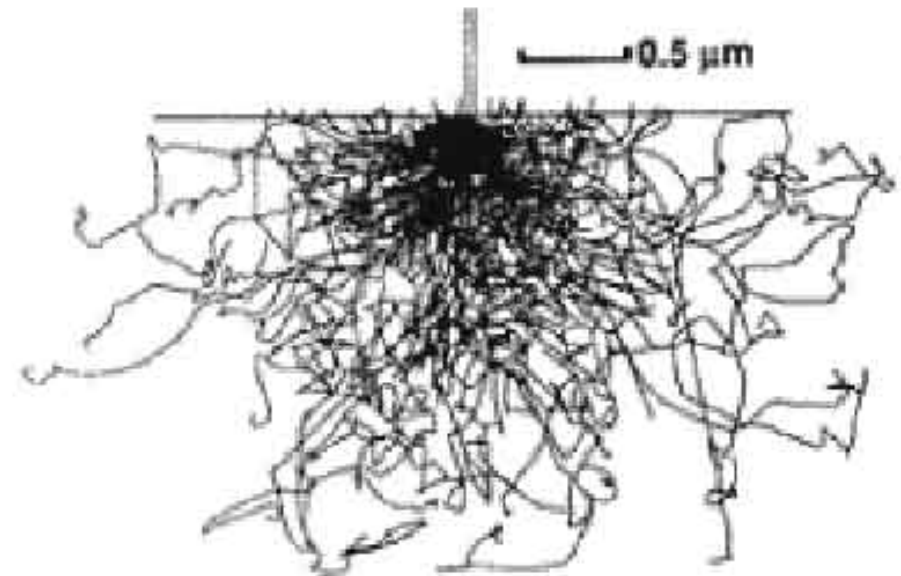


## Accelerating voltage

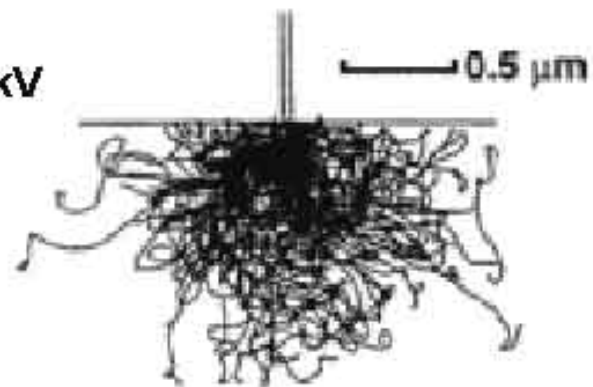
10 kV



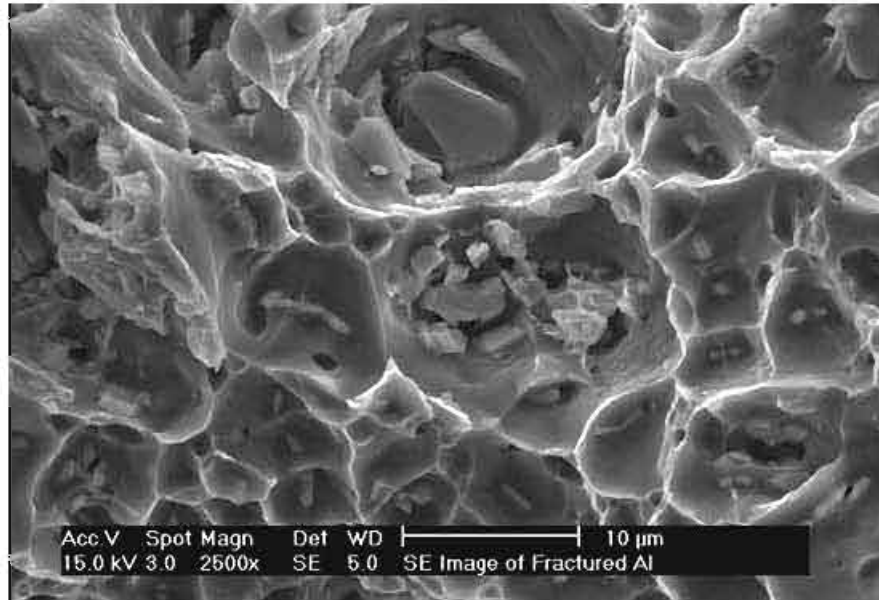
20 kV



30 kV

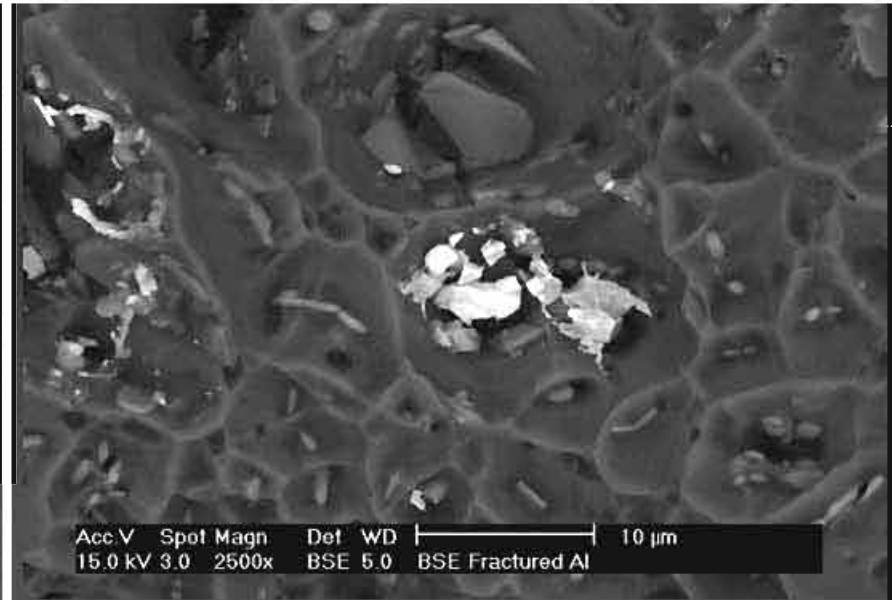


**Monte Carlo simulation of electron trajectories in iron as a function of accelerating voltage.**



SEI – Surface detail provided by only the secondary electrons that can escape from near the surface of the sample.

Secondary electron image  
(topographic image)



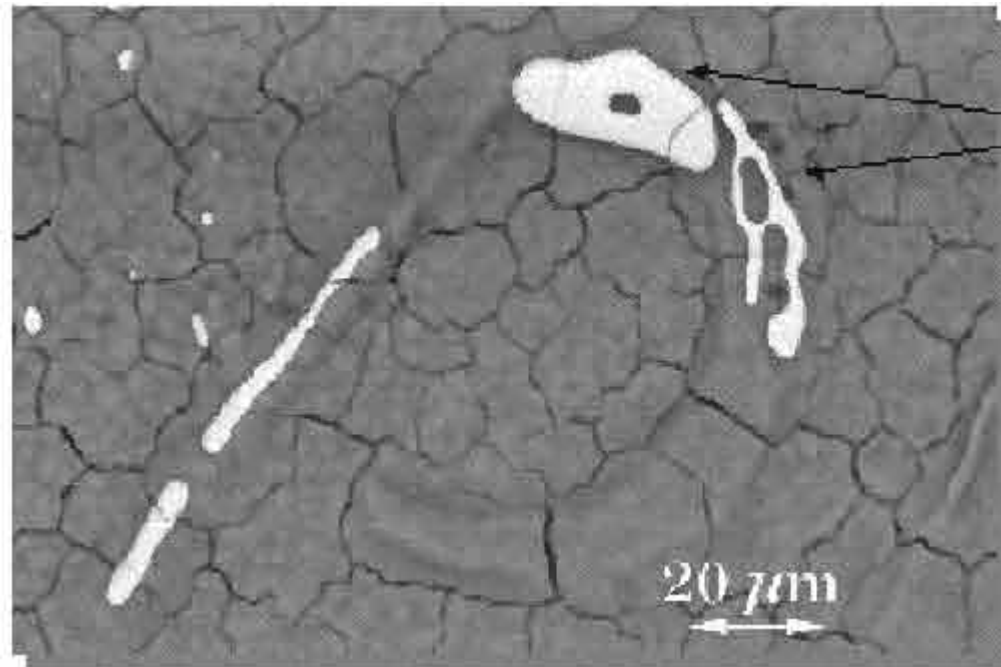
BSE – Z (atomic number) contrast is provided by electrons that "backscatter" in the direction of the incident beam.

Backscattered electron image  
(compositional image)

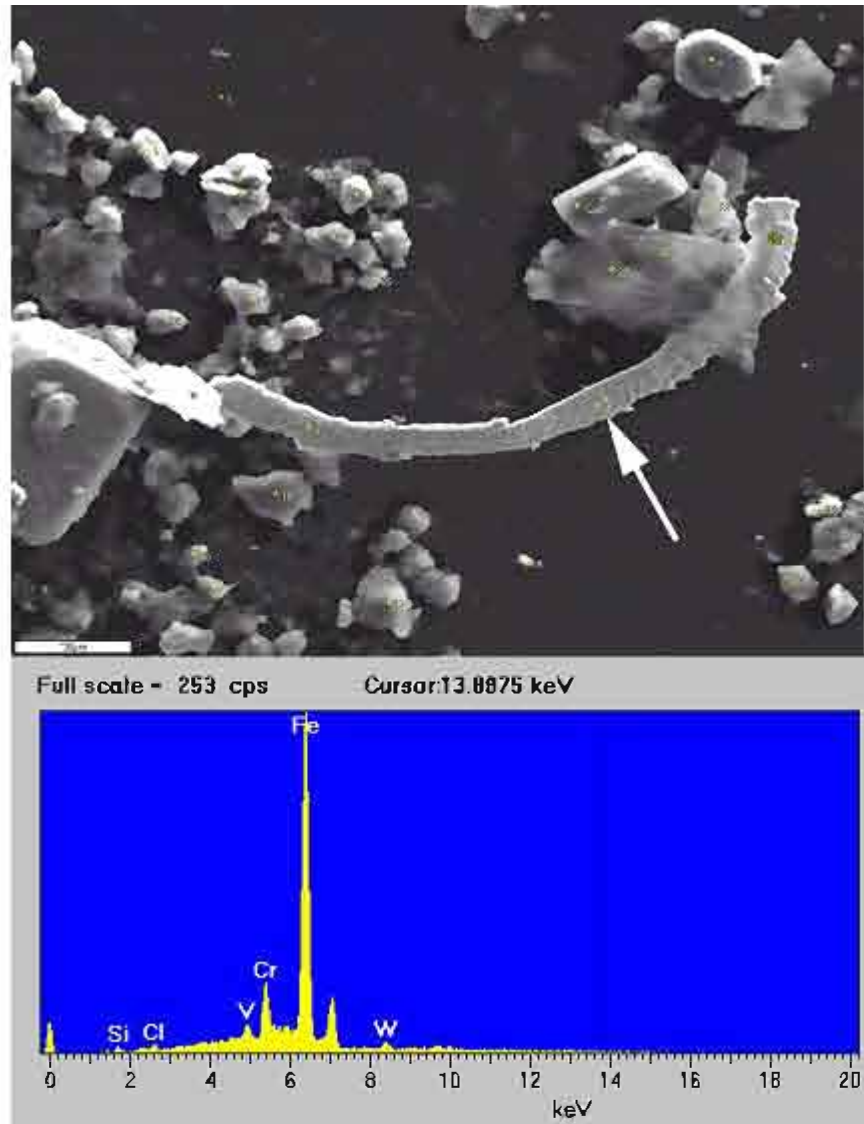


**BSE – atomic number contrast**

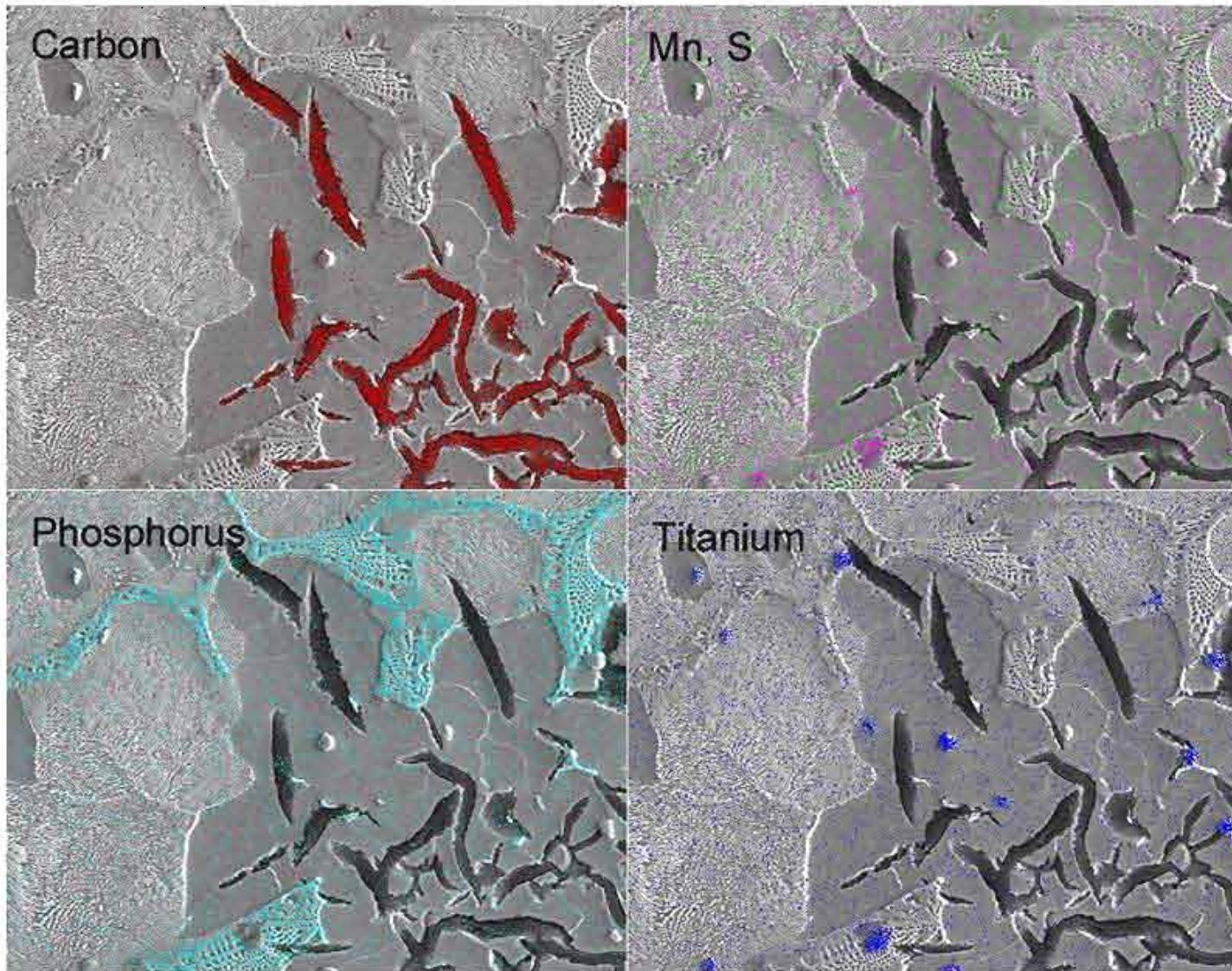
Oxidised  
silicon nitride



Y rich



Secondary electron image (SEI) and the X-ray energy dispersive spectrum (XEDS) obtained from the arrowed particle.



Compositional maps (or X-ray images)